

Webinar:

Reliability Calculation of Printed Circuit Boards and Assemblies under Reference, Test and Operating Conditions

Speaker:

Dipl.-Ing. David Dudek, Trainalytics GmbH, Project and Reliability Engineer

Date:

Wednesday September 16th, 2020

Time:

16:00 -17:00 CET (Amsterdam, Berlin, Paris, Rome, Stockholm - Summertime)

Host:



IPC brings to you another technical webinar to help electronics manufacturers build electronics better. Our topic will focus on the essential reliability criteria to determine the electronic assembly product lifetime. We all know reliability cannot be tested in the product. Critical reliability features must be identified and evaluated during the assembly development.

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Contents:

David will provide insights for the reliability and test engineer regarding the mechanism, dynamics and effective range (e.g. temperature, mechanical load and humidity) of degradation during the extended life tests on electronic assembly products. He will introduce:

- Appearance and Effect of Degradation Mechanisms
- Crack Growth in Solder Joints by thermomechanical Degradation
- Dendrite Growth by Electrochemical Migration
- Basic Reliability Statistics by Data Evaluation
- Reliability Test Planning
- Insight into the Purpose and Application of Industry Guidelines

Join us for this complimentary webinar and gain new insights on calculating reliability of printed circuit board assemblies.

This Webinar is a „taster“ for David’s reliability consulting and seminar offers. Please visit [www.trainalytics.de](http://www.trainalytics.de) for details under Training or Beratung. Call us, we speak English.